imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Zener Diode DZ36068D0L

DZ36068D0L Silicon epitaxial planar type

For surge absorption circuit

- Features
- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:02

Packaging

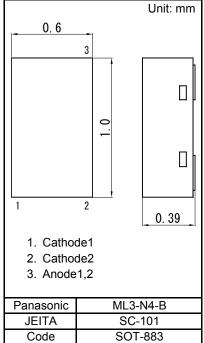
Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

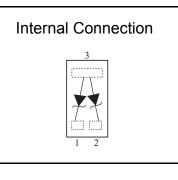
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit	
Total power dissipation ^{*1}	PT	200	mW	
Electrostatic discharge *2	ESD	±10	kV	
Junction temperature	Tj	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note) *1: PT = 200 mW achieved with a printed circuit board. (2 Diode total)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage *1, *2	VZ	IZ = 5 mA	6.46		7.14	V	
Zener operating resistance	RZ	IZ = 5 mA			30	Ω	
Zener rise operating resistance	RZK	IZ = 0.5 mA			60	Ω	
Reverse current	IR	VR = 4 V			0.1	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		3.1		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. *1: The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2: VZ guaranted 20 ms after current flow.

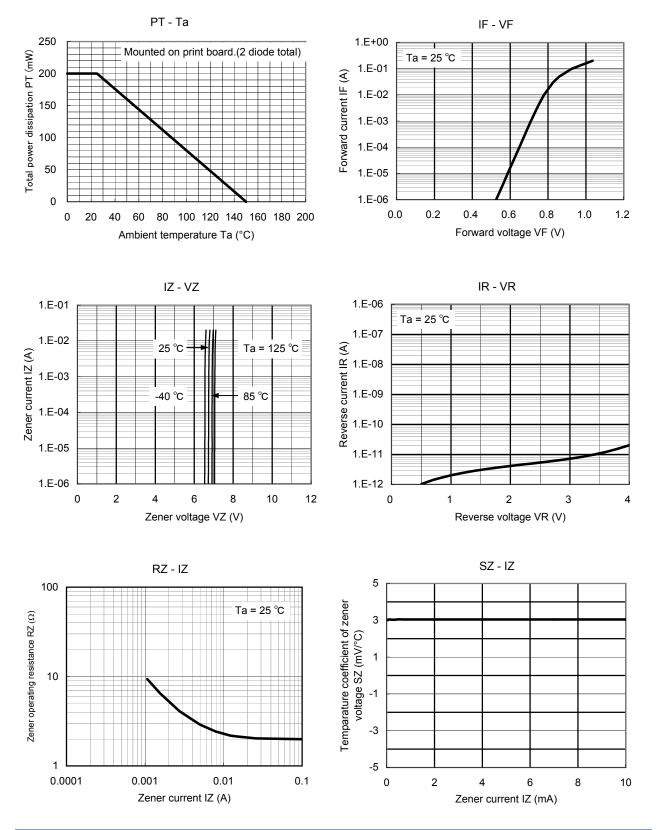
*3: Tj = 25°C to 150°C





Zener Diode DZ36068D0L

Technical Data (reference)

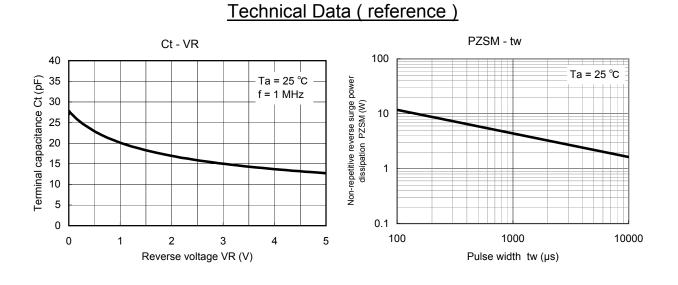


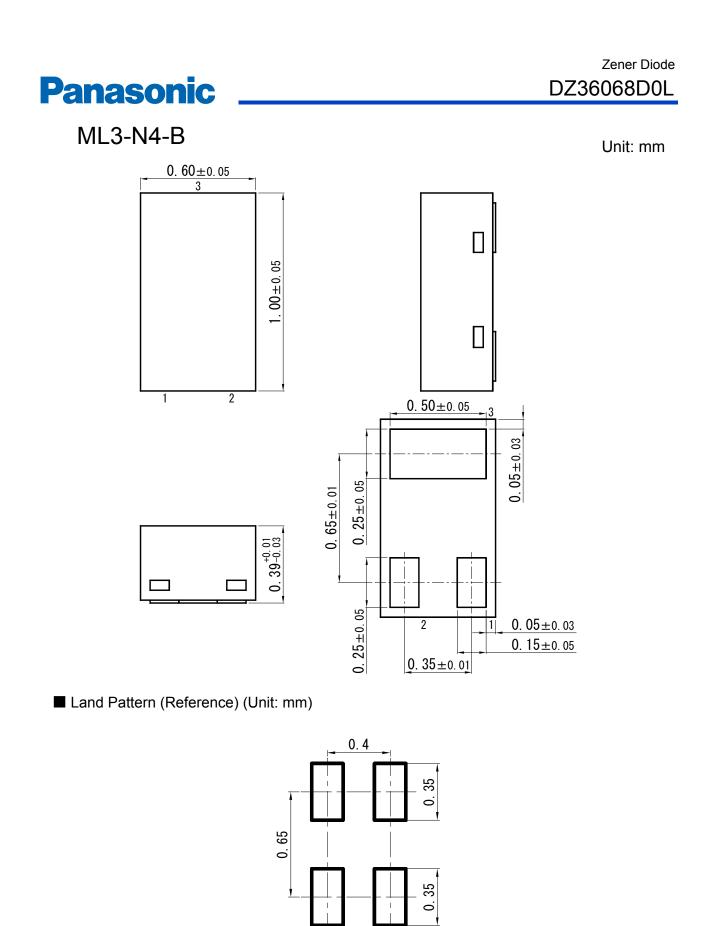
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Established : 2012-04-02 Revised : 2013-11-01



Zener Diode





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